

S/N Unknown

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Paul A. Farrar et al. Examiner: Unknown  
Serial No.: Unknown Group Art Unit: Unknown  
Filed: Herewith Docket: 303.469US3  
Title: THERMAL PROCESSING OF METAL ALLOYS FOR AN IMPROVED CMP  
PROCESS IN INTEGRATED CIRCUIT FABRICATION

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

When the above-identified patent application is taken up for consideration, please amend the application as follows:

**IN THE SPECIFICATION**

On page 1, please add the following new paragraph under the title:

A1 --This application is a Continuation of U.S. Application No. 09/038,252, filed on March 10, 1998.--  
now US 6,316,356

**IN THE CLAIMS**

Please cancel claims 1-17 after adding the following new claims.

- Sub B27
- A2
20. A memory device comprising:  
an array of memory cells;  
internal circuitry; and  
metal contacts and interconnects coupled to the memory cells and internal circuitry,  
wherein the metal contacts and interconnects are formed by annealing the memory at a  
temperature sufficient to drive alloy dopants into solid solution prior to polishing the memory  
device to remove portions of a metal layer and form the metal contacts and interconnects.
21. The memory device of claim 20 wherein the memory device is annealed following  
polishing of the memory device to increase the conductivity of the metal contacts and  
interconnects.